



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Features

- Dimension: 2.5mm x 2.0mm x 0.8mm.
- Low thermal resistance.
- Ceramic package with silicone resin.
- Small package with high efficiency.
- Surface mount technology.
- ESD protection.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 2a.
- Soldering methods: IR reflow soldering.
- RoHS compliant.

Application Note

Static electricity and surge damage the LEDs.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Typical Applications

PDA's

Room lighting

Architectural lighting

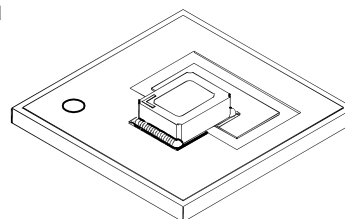
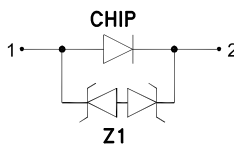
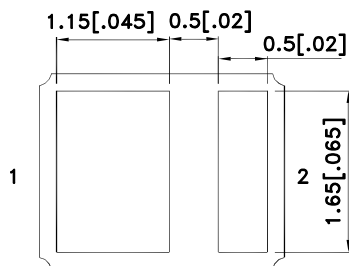
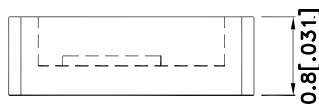
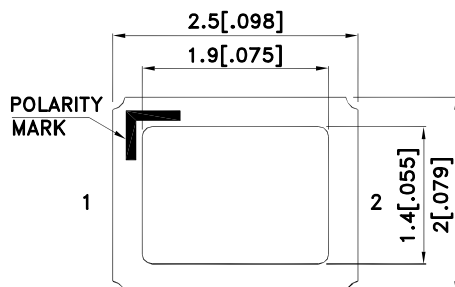
Decorative/pathway lighting

Front panel backlight

Exterior automotive lighting:

(brake lights, turn lights, backlighting)

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

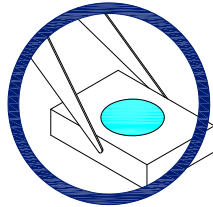


Handling Precautions

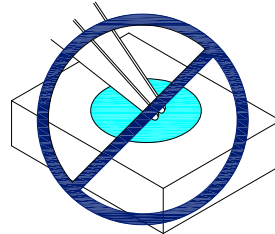
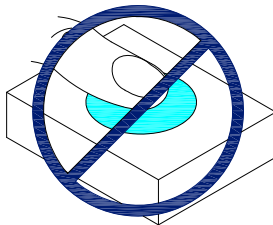
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

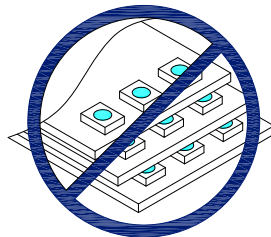
1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



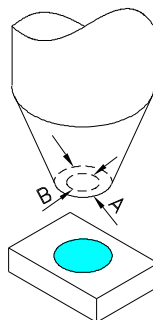
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



4.1. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.

4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.

4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Selection Guide

Part No.	Dice	luminous Intensity [2] Iv(mcd)@ 350mA		Φ_v (lm) [2] @ 350mA	Viewing Angle [1]
		Min.	Typ.	Typ.	2 θ 1/2
AT2520ZG10ZS-350MA	Green (AlGaInN)	8000	12000	50	120 °

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Absolute Maximum Ratings at T_A=25°C

Parameter	Symbol	Value	Unit
DC Forward Current [1]	I _F	350	mA
Peak Forward Current [2]	I _{FM}	500	mA
Power dissipation	P _D	1.3	W
Operating Temperature	T _{op}	-40 To +100	°C
Storage Temperature	T _{stg}	-40 To +120	°C
Reverse Voltage	V _R	5	V
Junction temperature[1]	T _J	120	°C
Thermal resistance [1] (Junction/ambient)	R _{th j-a}	75	°C/W
Thermal resistance [1] (Junction/solder point)	R _{th j-s}	28	°C/W
Electrostatic Discharge Threshold (HBM)		8000	V

Notes:

1. Results from mounting on metal core PCB, mounted on pc board-metal core PCB is recommend for lowest thermal resistance.
2. 1/10 Duty Cycle, 0.1ms Pulse Width.

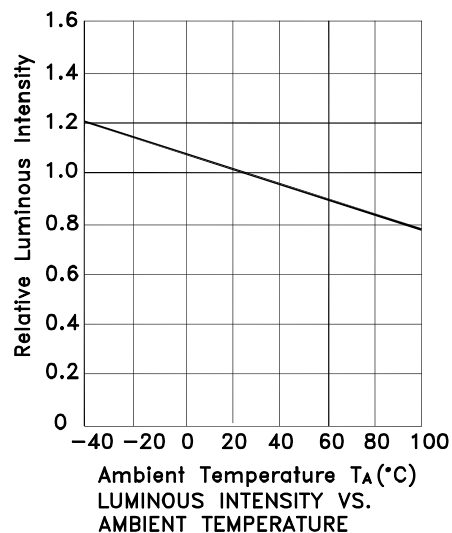
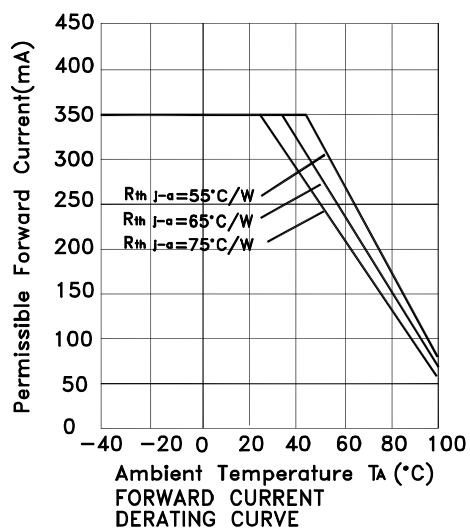
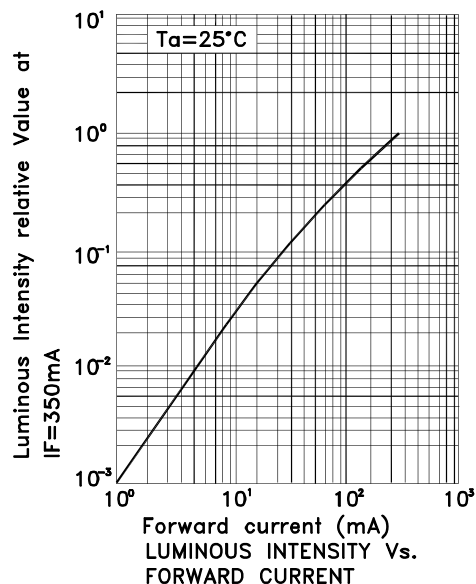
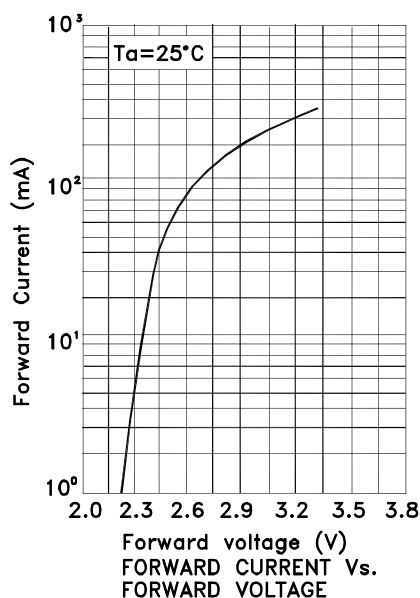
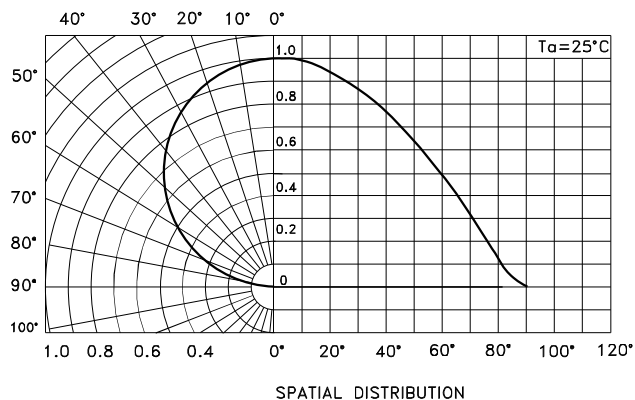
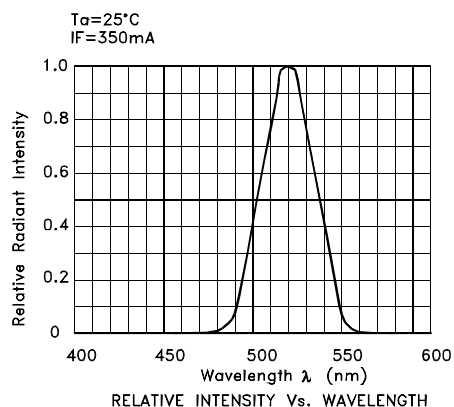
Electrical / Optical Characteristics at T_A = 25°C

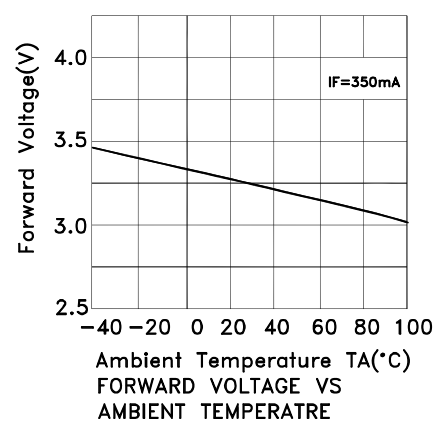
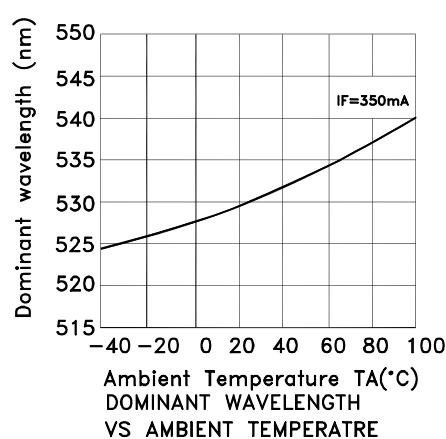
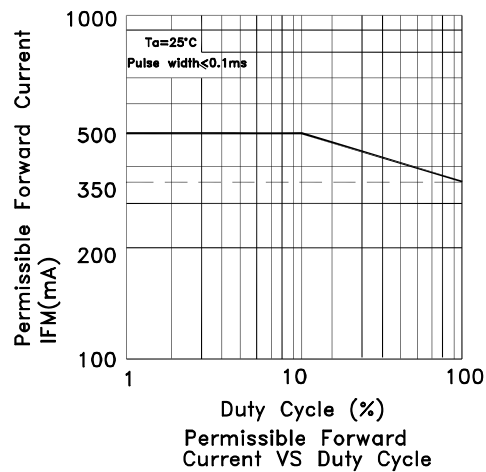
Parameter	Symbol	Value	Unit
Forward Voltage I _F = 350mA [Min.]	V _F [2]	2.7	V
Forward Voltage I _F = 350mA [Typ.]		3.3	
Forward Voltage I _F = 350mA [Max.]		3.8	
Allowable Reverse Current [Max.]	I _R	85	mA
Wavelength at peak emission I _F = 350mA [Typ.]	λ peak	520	nm
Dominant Wavelength I _F = 350mA [Typ.]	λ dom [1]	530	nm
Spectral bandwidth at 50% $\Phi_{REL MAX}$ I _F = 350mA [Typ.]	$\Delta\lambda$	35	nm
Temperature coefficient of λ peak I _F = 350mA, - 10 ° C ≤ T ≤ 100 ° C [Typ.]	TC λ peak	0.16	nm/°C
Temperature coefficient of λ dom I _F = 350mA, - 10 ° C ≤ T ≤ 100 ° C [Typ.]	TC λ dom	0.14	nm/°C
Temperature coefficient of V _F I _F = 350mA, - 10 ° C ≤ T ≤ 100 ° C [Typ.]	TC _v	-3.1	mV/°C

Notes:

1. Wavelength : + / -1nm.
2. Forward Voltage : + / - 0.1V.

AT2520ZG10ZS-350MA

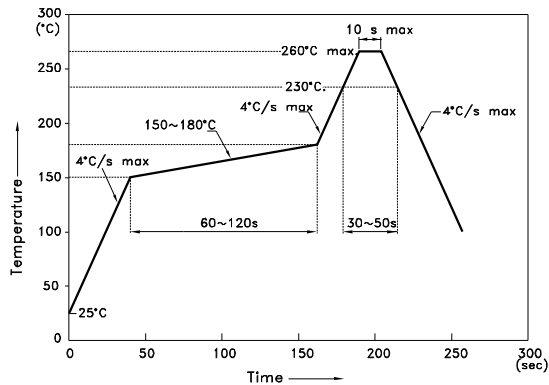




AT2520ZG10ZS-350MA

Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

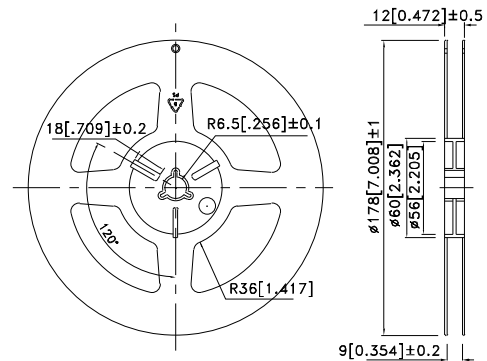
Reflow Soldering Profile For Lead-free SMT Process.



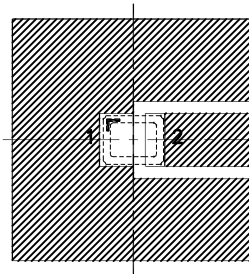
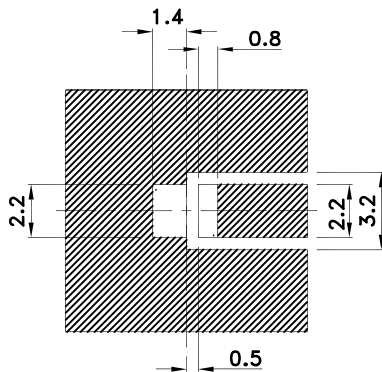
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Reel Dimension

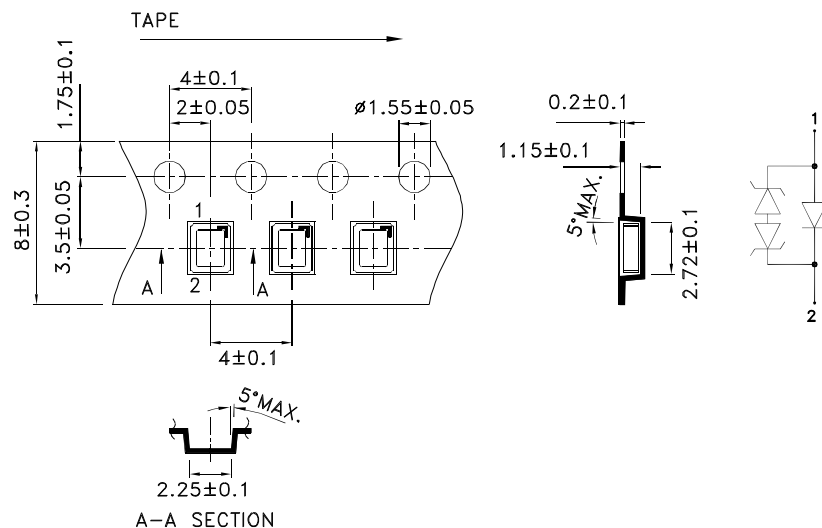


Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



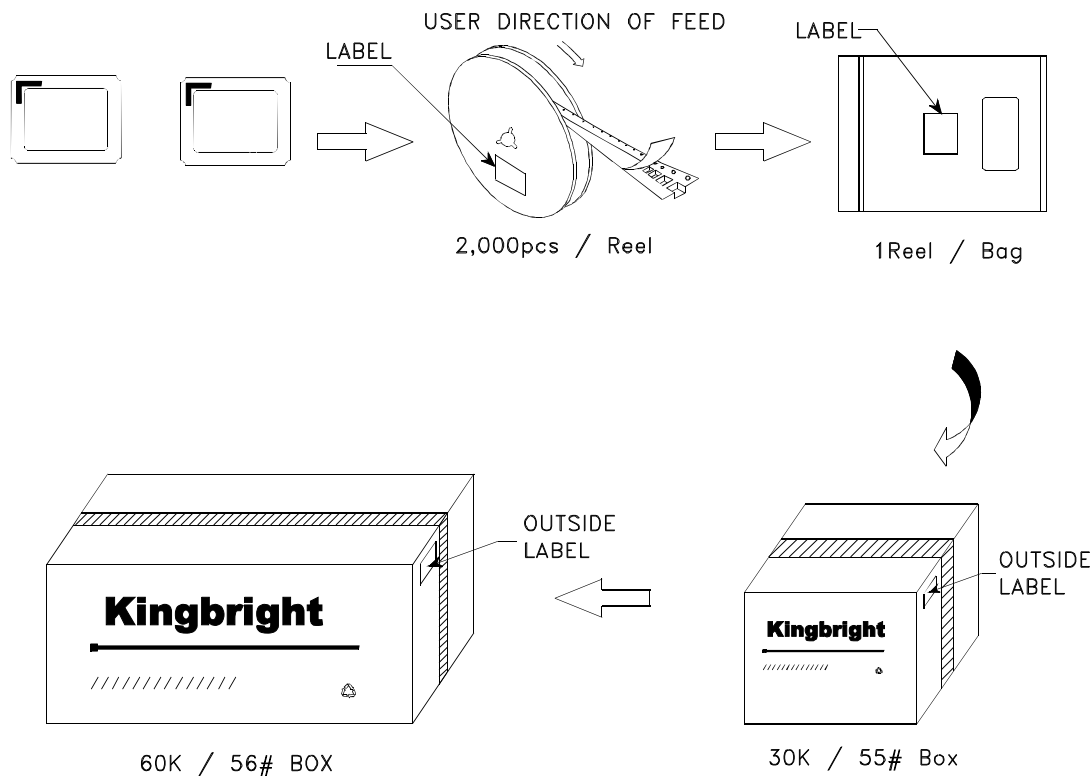
Solder resist

Tape Specifications (Units : mm)



PACKING & LABEL SPECIFICATIONS

AT2520ZG10ZS-350MA



Kingbright		
P/N0: AT2520xxx		
QTY: 2,000 pcs	Q.C.	Q C xx xx xxxx PASSED
S/N: XXXX		
CODE: XXX		
LOT NO:		
 xxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxx		
RoHS Compliant		